



#16/Amended
MAIL STOP RCE
PATENT
8013-4074
9/20/03

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of:

Hidemitsu AOKI et al.

Confirmation No. 6696

Serial No. 09/715,000

GROUP 2825

Filed November 20, 2000

Examiner Chuong A. Luu

IMPROVED SEMICONDUCTOR WAFER SURFACE
AND METHOD OF TREATING A SEMICONDUCTOR
WAFER SURFACE

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

September 16, 2003

Sir:

In response to the final Office Action mailed June 18, 2003, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 10 of this paper.